molex

Polymicro 200/230 PolyClad Fiber

200µm HPCF for Data-Communications Crimp and Cleave Compatible

CHARACTERISTICS

Step index

Low –OH, synthetic fused silica core, PolyClad™ hard polymer clad, ETFE buffer or jacket

Broad operating wavelength range, optimized at 650 and 850nm

Minimal connector offsets due to high clad/core diameter ratio

High tensile strength and minimal bend radius for high reliability

Crimp/cleave and epoxy/polish compatible

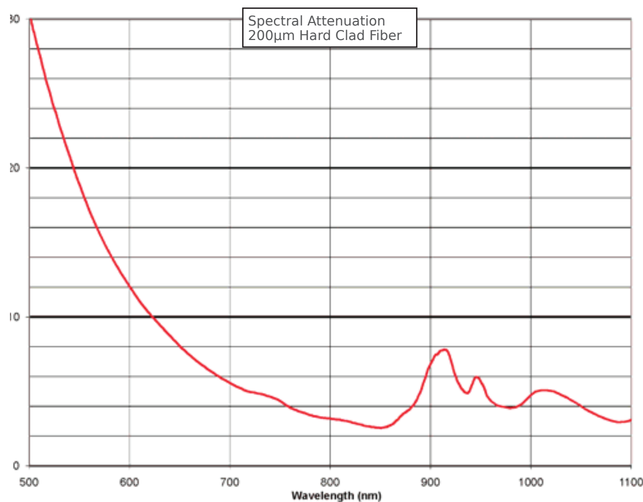
Large core and high na provides easy termination and high coupling efficiency to light source

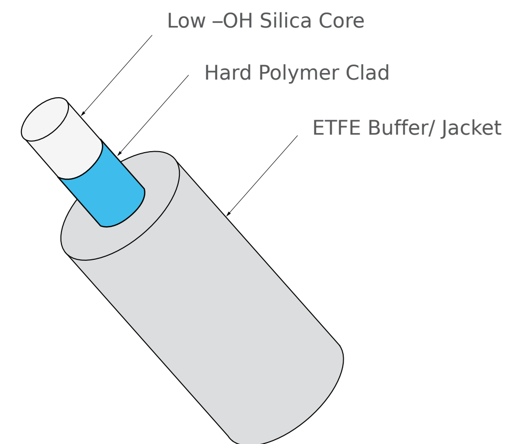
Chemically resistant

Flame retardant

Short-to-medium distance data communications for factory automation and process control

ROHS compliant





Specifications

Parameters	Specifications
Core Diameter	200 +/- 4µm
Cladding Diameter	230 +/- 10µm
Buffer Diameter	500 +/- 30µm
Core/Clad Offset	≤5µm
Core Material	Low–OH Synthetic Fused Silica, SiO_2
Cladding Material	PolyClad™ Hard Polymer
Buffer Material	ETFE
Numerical Aperture (NA)	0.37 +/- 0.02
Attenuation	≤ 6 dB/km at λ=850nm ≤ 10 dB/km at λ=650nm
Short-term Bend Radius	≥10mm
Long-term Bend Radius	≥16mm
Proof Test Level	≥150 kpsi (1.03GPa)
Operating Temperature	-65 to +125°C
Bandwidth at 850nm	≥20MHz-km
Standard Reel Length	2200m +/- 5%

Applications

Chemical plants

Refineries

Avionics

Automotive

Production/manufacturing plants

Mobile platforms

Wind power

Power plants

PLC’s

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